

**DOCKET NO. 01-C-084 (STMI01-01084)**  
**Customer No. 30425**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of : Harry Michael Siegel, et al.  
Serial No. : 10/066,245  
Filed : January 31, 2002  
For : METHOD FOR USING A PRE-FORMED FILM IN A TRANSFER  
MOLDING PROCESS FOR AN INTEGRATED CIRCUIT (AS  
AMENDED)  
Group No. : 1791  
Examiner : Edmund H. Lee  
Confirmation No. : 2782

**MAIL STOP ISSUE FEE**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**AMENDMENT UNDER 37 C.F.R. § 1.312**

Pursuant to 37 C.F.R. § 1.312, Applicant respectfully requests amendment the above-identified application as follows: